

## General Description

EZ-PD™ CCG2 is a USB Type-C controller that complies with the latest USB Type-C and PD standards. EZ-PD CCG2 provides a complete USB Type-C and USB Power Delivery port control solution for passive cables, active cables, and powered accessories. It can also be used in many upstream and downstream facing port applications. EZ-PD CCG2 uses Cypress's proprietary MOS8 technology with a 32-bit, 48-MHz ARM® Cortex®-M0 processor with 32-KB flash and integrates a complete Type-C Transceiver including the Type-C termination resistors  $R_P$ ,  $R_D$  and  $R_A$ .

## Applications

- USB Type-C EMCA cables
- USB Type-C powered accessories
- USB Type-C upstream facing ports
- USB Type-C downstream facing ports

## Features

### 32-bit MCU Subsystem

- 48-MHz ARM Cortex-M0 CPU
- 32-KB Flash
- 4-KB SRAM
- In-system reprogrammable

### Integrated Digital Blocks

- Integrated timers and counters to meet response times required by the USB-PD protocol
- Run-time reconfigurable serial communication block (SCB) with reconfigurable I<sup>2</sup>C, SPI, or UART functionality

### Clocks and Oscillators

- Integrated oscillator eliminating the need for external clock

## Type-C Support

- Integrated transceiver (baseband PHY)
- Integrated UFP ( $R_D$ ), EMCA ( $R_A$ ) termination resistors, and current sources for DFP ( $R_P$ )
- Supports one USB Type-C port

## Low-Power Operation

- 2.7-V to 5.5-V operation
- Two independent VCONN rails with integrated isolation between the two
- Independent supply voltage pin for GPIO that allows 1.71-V to 5.5-V signaling on the I/Os
- Reset: 1.0  $\mu$ A, Deep Sleep: 2.5  $\mu$ A, Sleep: 2.0 mA

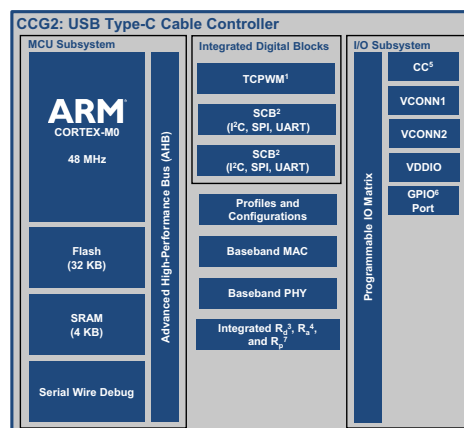
## System-Level ESD on CC and VCONN Pins

- $\pm 8$ -kV Contact Discharge and  $\pm 15$ -kV Air Gap Discharge based on IEC61000-4-2 level 4C

## Packages

- 1.63 mm  $\times$  2.03 mm, 20-ball wafer-level CSP (WL CSP) with 0.4-mm ball pitch
- 2.5 mm  $\times$  3.5 mm  $\times$  0.6 mm 14-pin DFN
- 4.0 mm  $\times$  4.0 mm, 0.55 mm 24-pin QFN
- Supports industrial ( $-40$  °C to  $+85$  °C) and extended industrial ( $-40$  °C to  $+105$  °C) temperature ranges

## Logic Block Diagram

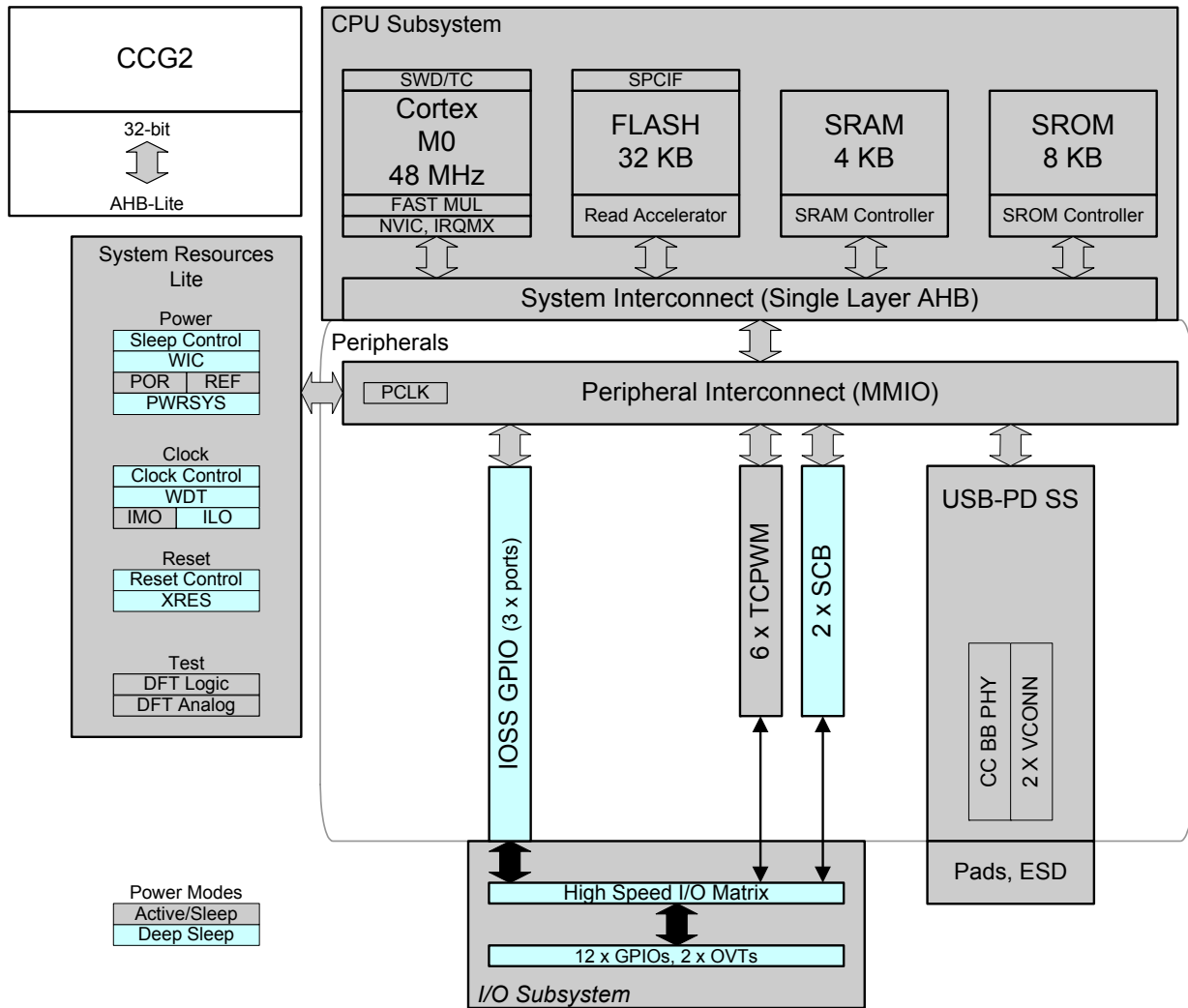


<sup>1</sup> Timer, counter, pulse-width modulation block  
<sup>2</sup> Serial communication block configurable as UART, SPI, or I<sup>2</sup>C  
<sup>3</sup> Termination resistor denoting a UFP  
<sup>4</sup> Termination resistor denoting an EMCA  
<sup>5</sup> Configuration Channel  
<sup>6</sup> General-purpose input/output  
<sup>7</sup> Current Sources to indicate a DFP

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Figure 1. EZ-PD CCG2 Block Diagram



## Functional Overview

### CPU and Memory Subsystem

#### CPU

The Cortex-M0 CPU in EZ-PD CCG2 is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. It mostly uses 16-bit instructions and executes a subset of the Thumb-2 instruction set. This enables fully compatible binary upward migration of the code to higher performance processors such as the Cortex-M3 and M4, thus enabling upward compatibility. The Cypress implementation includes a hardware multiplier that provides a 32-bit result in one cycle. It includes a nested vectored interrupt controller (NVIC) block with 32 interrupt inputs and also includes a Wakeup Interrupt Controller (WIC). The WIC can wake the processor up from the Deep Sleep mode, allowing power to be switched off to the main processor when the chip is in the Deep Sleep mode. The Cortex-M0 CPU provides a Non-Maskable Interrupt (NMI) input, which is made available to the user when it is not in use for system functions requested by the user.

The CPU also includes a serial wire debug (SWD) interface, which is a 2-wire form of JTAG. The debug configuration used for EZ-PD CCG2 has four break-point (address) comparators and two watchpoint (data) comparators.

#### Flash

The EZ-PD CCG2 device has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The flash block is designed to deliver 1 wait-state (WS) access time at 48 MHz and with 0-WS access time at 24 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average. Part of the flash module can be used to emulate EEPROM operation if required.

#### SROM

A supervisory ROM that contains boot and configuration routines is provided.

**USB-PD Subsystem (SS)**

EZ-PD CCG2 has a USB-PD subsystem consisting of a USB Type-C baseband transceiver and physical-layer logic. This transceiver performs the BMC and the 4b/5b encoding and decoding functions as well as the 1.2-V front end. This subsystem integrates the required termination resistors to identify the role of the EZ-PD CCG2 solution.  $R_A$  is used to identify EZ-PD CCG2 as an accessory or an electronically marked cable.  $R_D$  is used to identify EZ-PD CCG2 as a UFP in a hybrid cable or a dongle. When configured as a DFP, integrated current sources perform the role of  $R_P$  or pull-up resistors. These current sources can be programmed to indicate the complete range of current capacity on VBUS defined in the Type-C spec. EZ-PD CCG2 responds to all USB-PD communication. The

EZ-PD CCG2 USB-PD sub-system can be configured to respond to SOP, SOP', or SOP'' messaging.

The USB-PD sub-system contains a 8-bit SAR (Successive Approximation Register) ADC for analog to digital conversions. The ADC includes a 8-bit DAC and a comparator. The DAC output forms the positive input of the comparator. The negative input of the comparator is from a 4-input multiplexer. The four inputs of the multiplexer are a pair of global analog multiplexers an internal bandgap voltage and an internal voltage proportional to the absolute temperature. All GPIO inputs can be connected to the global Analog Multiplex Buses through a switch at each GPIO that can enable that GPIO to be connected to the mux bus for ADC use. The CC1, CC2 and RD1 pins are not available to connect to the mux busses.

**Figure 2. USB-PD Subsystem**



**System Resources**

*Power System*

The power system is described in detail in the section [Power on page 8](#). It provides assurance that voltage levels are as required for each respective mode and either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (Brown-Out Detect (BOD)) or interrupts (Low Voltage Detect (LVD)). EZ-PD CCG2 can operate from three different power sources over the range of 2.7 to 5.5 V and has three different power modes, transitions between which are managed by the power system. EZ-PD CCG2 provides Sleep and Deep Sleep low-power modes.

*Clock System*

The clock system for EZ-PD CCG2 consists of the Internal Main Oscillator (IMO) and the Internal Low-power Oscillator (ILO).

## Peripherals

### Serial Communication Blocks (SCB)

EZ-PD CCG2 has two SCBs, which can be configured to implement an I<sup>2</sup>C, SPI, or UART interface. The hardware I<sup>2</sup>C blocks implement full multi-master and slave interfaces capable of multimaster arbitration. In the SPI mode, the SCB blocks can be configured to act as master or slave.

In the I<sup>2</sup>C mode, the SCB blocks are capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and have flexible buffering options to reduce interrupt overhead and latency for the CPU. These blocks also support I<sup>2</sup>C that creates a mailbox address range in the memory of EZ-PD CCG2 and effectively reduce I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the blocks support 8-deep FIFOs for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduce the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripherals are compatible with the I<sup>2</sup>C Standard-mode, Fast-mode, and Fast-mode Plus devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/Os are implemented with GPIO in open-drain modes.

The I<sup>2</sup>C port on SCB 1 block of EZ-PD CCG2 is not completely compliant with the I<sup>2</sup>C spec in the following respects:

- The GPIO cells for SCB 1's I<sup>2</sup>C port are not overvoltage-tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.
- Fast-mode Plus has an I<sub>OL</sub> specification of 20 mA at a V<sub>OL</sub> of 0.4 V. The GPIO cells can sink a maximum of 8-mA I<sub>OL</sub> with a V<sub>OL</sub> maximum of 0.6 V.
- Fast-mode and Fast-mode Plus specify minimum Fall times, which are not met with the GPIO cell; Slow strong mode can help meet this spec depending on the bus load.

### Timer/Counter/PWM Block (TCPWM)

EZ-PD CCG2 has six TCPWM blocks. Each implements a 16-bit timer, counter, pulse-width modulator (PWM), and quadrature decoder functionality. The block can be used to measure the period and pulse width of an input signal (timer), find the number of times a particular event occurs (counter), generate PWM signals, or decode quadrature signals.

## GPIO

EZ-PD CCG2 has up to 10 GPIOs in addition to the I<sup>2</sup>C and SWD pins, which can also be used as GPIOs. The I<sup>2</sup>C pins from SCB 0 are overvoltage-tolerant. The number of available GPIOs vary with the package. The GPIO block implements the following:

- Seven drive strength modes:
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTTL)
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Hold mode for latching previous state (used for retaining I/O state in Deep Sleep mode)
- Selectable slew rates for dV/dt related noise control to improve EMI

During power-on and reset, the I/O pins are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

**Pinouts**

Group	Name	Pin Map 24-QFN	Ball Location 20-CSP	Pin Map 14-DFN	Description
USB Type-C Port	CC1	2	B4	3	USB PD connector detect/Configuration Channel 1
	CC2	1	A4	N/A	USB PD connector detect/Configuration Channel 2
	RD1	3	B3	N/A	Dedicated Rd resistor pin for CC1 Must be left open for cable applications and connected together with CC1 ball for UFP or DFP with dead battery applications
GPIOs and serial interfaces	GPIO	22	C3	N/A	GPIO / SPI_0_CLK / UART_0_RX
	GPIO	18	D3	13	GPIO / SPI_0_MOSI / UART_0_TX
	GPIO	13	C2	10	GPIO / I2C_1_SDA / SPI_1_MISO / UART_1_RX
	GPIO	10	D2	N/A	GPIO / I2C_1_SCL / SPI_1_CLK / UART_1_TX
	GPIO	15	B2	11	GPIO / SPI_1_SEL / UART_1_RTS
	GPIO	14	N/A	N/A	GPIO
	GPIO	17	N/A	N/A	GPIO
	GPIO	21	N/A	N/A	GPIO
	GPIO	23	N/A	N/A	GPIO
	GPIO	24	N/A	N/A	GPIO
	I2C_0_SCL	20	A3	1	GPIO / I2C_0_SCL / SPI_0_MISO / UART_0_RTS
	I2C_0_SDA	19	A2	14	GPIO / I2C_0_SDA / SPI_0_SEL / UART_0_CTS
	SWD_IO	11	E2	8	SWD IO / GPIO / UART_1_CTS / SPI_1_MOSI
SWD_CLK	12	D1	9	SWD clock / GPIO	
RESET	XRES	16	B1	12	Reset input
POWER	VCONN1	5	E4	5	VCONN 1 input (4.0 V to 5.5 V)
	VCONN2	4	C4	4	VCONN 2 input (4.0 V to 5.5 V)
	VDDIO	8	E1	N/A	1.71-V to 5.5-V supply for I/Os
	VCCD	7	A1	6	1.8-V regulator output for filter capacitor
	VDDD	9	E3	7	VDDD supply input/output (2.7 V to 5.5 V)
	VDDD	6			VDDD supply input/output (2.7 V to 5.5 V)
	VSS	EPAD	N/A	EPAD	Ground supply
	VSS		D4	2	Ground supply
	VSS		C1		Ground supply

**Figure 3. 20-ball WLCSP EZ-PD CCG2 Ball Map (Bottom (Balls Up) View)**



**Figure 4. 14-pin DFN Pin Map (Top View)**



**Figure 5. 24-Pin QFN Pin Map (Top View)**



## Power

The following power system diagram shows the set of power supply pins as implemented in EZ-PD CCG2.

EZ-PD CCG2 can operate from three different power sources. VCONN1 and VCONN2 pins can be used as connections to the VCONN pins on a Type-C plug of a cable or VCONN-powered accessory. Each of these inputs support operation over 4.0 to 5.5 V. An internal isolation between VCONN1 and VCONN2 pins is provided allowing them to be at different levels simultaneously. CCG2 can be used in EMCA applications with only one or both VCONN pins as power sources. This is illustrated later in the section on Applications. Besides being power inputs, each VCONN pin is also internally connected to a  $R_A$  termination resistor required for EMCA and VCONN-powered accessories.

EZ-PD CCG2 can also be operated from 2.7 to 5.5 V when operated from the VDDD supply pin. VCONN-powered accessory applications require that CCG2 work down to 2.7 V. In such applications, both the VDDD and VCONN pins should be connected to the VCONN pin of the Type-C plug in the accessory.

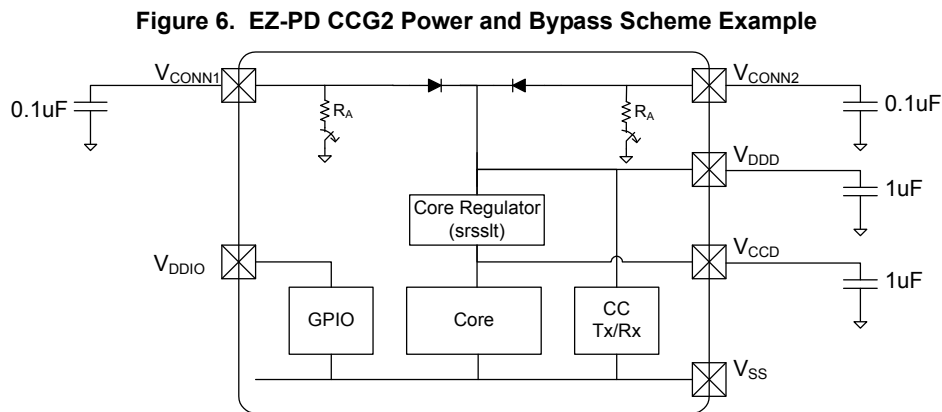
In UFP, DFP, and DRP applications, CCG2 can be operated from VDDD as the only supply input. In such applications, the VCONN pins are left open. In DFP applications, the lowest VDDD level that CCG2 can operate is 3.0 V due to the need to support disconnect detection thresholds of up to 2.7 V.

A separate I/O supply pin, VDDIO, allows the GPIOs to operate at levels from 1.71 to 5.5 V. The VDDIO pin can be equal to or less than the voltages connected to the VCONN1, VCONN2, and VDDD pins. The independent VDDIO supply is not available on the 14-DFN package. On this package, the VDDIO rail is internally connected to the VDDD rails.

The VCCD output of EZ-PD CCG2 must be bypassed to ground via an external capacitor (in the range of 1 to 1.6  $\mu\text{F}$ ; X5R ceramic or better).

Bypass capacitors must be used from VDDD and VCONN pins to ground; typical practice for systems in this frequency range is to use a 0.1- $\mu\text{F}$  capacitor. Note that these are simply rules of thumb and that for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of the power supply bypass capacitors is shown in [Figure 6](#).





**Application Diagrams**

**Figure 7. Passive EMCA Application – Single EZ-PD CCG2 Per Cable**





**Figure 10. Dual Role Port (DRP) Application**



**Figure 11. Downstream Facing Port (DFP) Application**



Figure 12. USB Type-C to HDMI/DVI/VGA Dongle Application Diagram





Figure 14. CCG2 in Dock/Monitor Application Diagram



CCG2 connected on the Upstream Port

CCG2 connected on the Downstream Port

## Electrical Specifications

### Absolute Maximum Ratings

**Table 1. Absolute Maximum Ratings<sup>[1]</sup>**

Parameter	Description	Min	Typ	Max	Units	Details/Conditions
V <sub>DDD_MAX</sub>	Digital supply relative to V <sub>SS</sub>	-0.5	-	6	V	Absolute max
V <sub>CONN1_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	-	-	6	V	Absolute max
V <sub>CONN2_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	-	-	6	V	Absolute max
V <sub>DDIO_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	-	-	6	V	Absolute max
V <sub>GPIO_ABS</sub>	GPIO voltage	-0.5	-	V <sub>DDIO</sub> + 0.5	V	Absolute max
V <sub>CC_ABS</sub>	Absolute max voltage for CC1 and CC2 pins	-	-	6	V	Absolute max
I <sub>GPIO_ABS</sub>	Maximum current per GPIO	-25	-	25	mA	Absolute max
I <sub>GPIO_injection</sub>	GPIO injection current, Max for V <sub>IH</sub> > V <sub>DDD</sub> , and Min for V <sub>IL</sub> < V <sub>SS</sub>	-0.5	-	0.5	mA	Absolute max, current injected per pin
ESD_HBM	Electrostatic discharge human body model	2200	-	-	V	-
ESD_CDM	Electrostatic discharge charged device model	500	-	-	V	-
LU	Pin current for latch-up	-200	-	200	mA	-
ESD_IEC_CON	Electrostatic discharge IEC61000-4-2	8000	-	-	V	Contact discharge on CC1, CC2, VCONN1, and VCONN2 pins
ESD_IEC_AIR	Electrostatic discharge IEC61000-4-2	15000	-	-	V	Air discharge for pins CC1, CC2, VCONN1, and VCONN2

**Note**

- Usage above the absolute maximum conditions listed in Table 1 may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.



**Device Level Specifications**

All specifications are valid for  $-40\text{ }^{\circ}\text{C} \leq T_A \leq 85\text{ }^{\circ}\text{C}$  and  $T_J \leq 100\text{ }^{\circ}\text{C}$ , except where noted. Specifications are valid for 3.0 V to 5.5 V, except where noted.

**Table 2. DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.PWR#1	V <sub>DDD</sub>	Power supply input voltage	2.7	–	5.5	V	UFP Applications
SID.PWR#1_A	V <sub>DDD</sub>	Power supply input voltage	3.0	–	5.5	V	DFP/DRP Applications
SID.PWR#23	V <sub>CONN1</sub>	Power supply input voltage	4.0	–	5.5	V	–
SID.PWR#23_A	V <sub>CONN2</sub>	Power supply input voltage	4.0	–	5.5	V	–
SID.PWR#13	V <sub>DDIO</sub>	GPIO power supply	1.71	–	5.5	V	–
SID.PWR#24	V <sub>CCD</sub>	Output voltage (for core logic)	–	1.8	–	V	–
SID.PWR#15	C <sub>EFC</sub>	External regulator voltage bypass on V <sub>CCD</sub>	1	1.3	1.6	μF	X5R ceramic or better
SID.PWR#16	C <sub>EXC</sub>	Power supply decoupling capacitor on V <sub>DDD</sub>	–	1	–	μF	X5R ceramic or better
SID.PWR#25		Power Supply Decoupling Capacitor on V <sub>CONN1</sub> and V <sub>CONN2</sub>	–	0.1	–	μF	X5R ceramic or better
<b>Active Mode, V<sub>DDD</sub> = 2.7 to 5.5 V. Typical values measured at V<sub>DD</sub> = 3.3 V.</b>							
SID.PWR#12	I <sub>DD12</sub>	Supply current	–	7.5	–	mA	V <sub>CONN1</sub> or V <sub>CONN2</sub> = 5 V, T <sub>A</sub> = 25 °C, CC I/O IN Transmit or Receive, R <sub>A</sub> disconnected, no I/O sourcing current, CPU at 12 MHz
<b>Sleep Mode, V<sub>DDD</sub> = 2.7 to 5.5 V</b>							
SID25A	I <sub>DD20A</sub>	I <sup>2</sup> C wakeup. WDT ON. IMO at 48 MHz	–	2.0	3.0	mA	V <sub>DDD</sub> = 3.3 V, T <sub>A</sub> = 25 °C, all blocks except CPU are ON, CC I/O ON, no I/O sourcing current
<b>Deep Sleep Mode, V<sub>DDD</sub> = 2.7 to 3.6 V (Regulator on)</b>							
SID_DS_RA	I <sub>DD_DS_RA</sub>	V <sub>CONN1</sub> = 5.0, R <sub>A</sub> termination disabled	–	100	–	μA	V <sub>CONN1</sub> , V <sub>CONN2</sub> = 5 V, T <sub>A</sub> = 25 °C. R <sub>A</sub> termination disabled on V <sub>CONN1</sub> and V <sub>CONN2</sub> , see SID.PD.7. VCONN leaker circuits turned off during deep sleep
SID34	I <sub>DD29</sub>	V <sub>DDD</sub> = 2.7 to 3.6 V. I <sup>2</sup> C wakeup and WDT ON	–	50	–	μA	R <sub>A</sub> switch disabled on V <sub>CONN1</sub> and V <sub>CONN2</sub> . V <sub>DDD</sub> = 3.3 V, T <sub>A</sub> = 25 °C
SID_DS	I <sub>DD_DS</sub>	V <sub>DDD</sub> = 2.7 to 3.6 V. CC wakeup ON	–	2.5	–	μA	Power source = V <sub>DDD</sub> , Type-C not attached, CC enabled for wakeup, R <sub>p</sub> disabled
<b>XRES Current</b>							
SID307	I <sub>DD_XR</sub>	Supply current while XRES asserted	–	1	10	μA	–

**Table 3. AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#4	F <sub>CPU</sub>	CPU frequency	DC	–	48	MHz	3.0 V ≤ V <sub>DD</sub> ≤ 5.5 V
SID.PWR#20	T <sub>SLEEP</sub>	Wakeup from sleep mode	–	0	–	μs	Guaranteed by characterization
SID.PWR#21	T <sub>DEEPSLEEP</sub>	Wakeup from Deep Sleep mode	–	–	35	μs	24-MHz IMO. Guaranteed by characterization
SID.XRES#5	T <sub>XRES</sub>	External reset pulse width	5	–	–	μs	Guaranteed by characterization
SYS.FES#1	T <sub>PWR_RDY</sub>	Power-up to “Ready to accept I2C / CC command”	–	5	25	ms	Guaranteed by characterization

I/O

**Table 4. I/O DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.GIO#37	V <sub>IH</sub> <sup>[2]</sup>	Input voltage HIGH threshold	0.7 × V <sub>DDIO</sub>	–	–	V	CMOS input
SID.GIO#38	V <sub>IL</sub>	Input voltage LOW threshold	–	–	0.3 × V <sub>DDIO</sub>	V	CMOS input
SID.GIO#39	V <sub>IH</sub> <sup>[2]</sup>	LVTTL input, V <sub>DDIO</sub> < 2.7 V	0.7 × V <sub>DDIO</sub>	–	–	V	–
SID.GIO#40	V <sub>IL</sub>	LVTTL input, V <sub>DDIO</sub> < 2.7 V	–	–	0.3 × V <sub>DDIO</sub>	V	–
SID.GIO#41	V <sub>IH</sub> <sup>[2]</sup>	LVTTL input, V <sub>DDIO</sub> ≥ 2.7 V	2.0	–	–	V	–
SID.GIO#42	V <sub>IL</sub>	LVTTL input, V <sub>DDIO</sub> ≥ 2.7 V	–	–	0.8	V	–
SID.GIO#33	V <sub>OH</sub>	Output voltage HIGH level	V <sub>DDIO</sub> – 0.6	–	–	V	I <sub>OH</sub> = 4 mA at 3-V V <sub>DDIO</sub>
SID.GIO#34	V <sub>OH</sub>	Output voltage HIGH level	V <sub>DDIO</sub> – 0.5	–	–	V	I <sub>OH</sub> = 1 mA at 1.8-V V <sub>DDIO</sub>
SID.GIO#35	V <sub>OL</sub>	Output voltage LOW level	–	–	0.6	V	I <sub>OL</sub> = 4 mA at 1.8-V V <sub>DDIO</sub>
SID.GIO#36	V <sub>OL</sub>	Output voltage LOW level	–	–	0.6	V	I <sub>OL</sub> = 8 mA at 3 V V <sub>DDIO</sub>
SID.GIO#5	R <sub>PULLUP</sub>	Pull-up resistor	3.5	5.6	8.5	kΩ	–
SID.GIO#6	R <sub>PULLDOWN</sub>	Pull-down resistor	3.5	5.6	8.5	kΩ	–
SID.GIO#16	I <sub>IL</sub>	Input leakage current (absolute value)	–	–	2	nA	25 °C, V <sub>DDIO</sub> = 3.0 V. Guaranteed by characterization
SID.GIO#17	C <sub>IN</sub>	Input capacitance	–	–	7	pF	Guaranteed by characterization
SID.GIO#43	V <sub>HYSTTL</sub>	Input hysteresis LVTTL	25	40	–	mV	V <sub>DDIO</sub> ≥ 2.7 V. Guaranteed by characterization.
SID.GPIO#44	V <sub>HYS-CMOS</sub>	Input hysteresis CMOS	0.05 × V <sub>DDIO</sub>	–	–	mV	Guaranteed by characterization
SID69	I <sub>DIODE</sub>	Current through protection diode to V <sub>DDIO</sub> /V <sub>SS</sub>	–	–	100	μA	Guaranteed by characterization
SID.GIO#45	I <sub>TOT-GPIO</sub>	Maximum total source or sink chip current	–	–	200	mA	Guaranteed by characterization

**Note**

 2. V<sub>IH</sub> must not exceed V<sub>DDIO</sub> + 0.2 V.

**Table 5. I/O AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID70	T <sub>RISEF</sub>	Rise time	2	–	12	ns	3.3-V V <sub>DDIO</sub> , Cload = 25 pF
SID71	T <sub>FALLF</sub>	Fall time	2	–	12	ns	3.3-V V <sub>DDIO</sub> , Cload = 25 pF

*XRES*
**Table 6. XRES DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.XRES#1	V <sub>IH</sub>	Input voltage HIGH threshold	0.7 × V <sub>DDIO</sub>	–	–	V	CMOS input
SID.XRES#2	V <sub>IL</sub>	Input voltage LOW threshold	–	–	0.3 × V <sub>DDIO</sub>	V	CMOS input
SID.XRES#3	C <sub>IN</sub>	Input capacitance	–	–	7	pF	Guaranteed by characterization
SID.XRES#4	V <sub>HYSXRES</sub>	Input voltage hysteresis	–	–	0.05 × V <sub>DDIO</sub>	mV	Guaranteed by characterization

## Digital Peripherals

The following specifications apply to the Timer/Counter/PWM peripherals in the Timer mode.

*Pulse Width Modulation (PWM) for GPIO Pins*
**Table 7. PWM AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.TCPWM.3	T <sub>CPWMFREQ</sub>	Operating frequency	–	F <sub>c</sub>	–	MHz	F <sub>c</sub> max = CLK_SYS. Maximum = 48 MHz.
SID.TCPWM.4	T <sub>PWMENEXT</sub>	Input trigger pulse width	–	2/F <sub>c</sub>	–	ns	For all Trigger Events
SID.TCPWM.5	T <sub>PWMEXT</sub>	Output trigger pulse width	–	2/F <sub>c</sub>	–	ns	Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs
SID.TCPWM.5A	T <sub>CRES</sub>	Resolution of counter	–	1/F <sub>c</sub>	–	ns	Minimum time between successive counts
SID.TCPWM.5B	PWM <sub>RES</sub>	PWM resolution	–	1/F <sub>c</sub>	–	ns	Minimum pulse width of PWM output
SID.TCPWM.5C	Q <sub>RES</sub>	Quadrature inputs resolution	–	1/F <sub>c</sub>	–	ns	Minimum pulse width between quadrature-phase inputs

*I<sup>2</sup>C*
**Table 8. Fixed I<sup>2</sup>C DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID149	I <sub>I2C1</sub>	Block current consumption at 100 kbps	–	–	60	μA	–
SID150	I <sub>I2C2</sub>	Block current consumption at 400 kbps	–	–	185	μA	–
SID151	I <sub>I2C3</sub>	Block current consumption at 1 Mbps	–	–	390	μA	–
SID152	I <sub>I2C4</sub>	I <sup>2</sup> C enabled in Deep Sleep mode	–	–	1.4	μA	–

**Table 9. Fixed I<sup>2</sup>C AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID153	F <sub>I2C1</sub>	Bit rate	–	–	1	Mbps	–

**Table 10. Fixed UART DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbits/sec	–	–	125	μA	Guaranteed by characterization
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbits/sec	–	–	312	μA	Guaranteed by characterization

**Table 11. Fixed UART AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	–	–	1	Mbps	Guaranteed by characterization

**Table 12. Fixed SPI DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	I <sub>SPI1</sub>	Block current consumption at 1Mbits/sec	–	–	360	μA	Guaranteed by characterization
SID164	I <sub>SPI2</sub>	Block current consumption at 4 Mbits/sec	–	–	560	μA	Guaranteed by characterization
SID165	I <sub>SPI3</sub>	Block current consumption at 8 Mbits/sec	–	–	600	μA	Guaranteed by characterization

**Table 13. Fixed SPI AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	F <sub>SPI</sub>	SPI Operating frequency (Master; 6X oversampling)	–	–	8	MHz	Guaranteed by characterization

**Table 14. Fixed SPI Master Mode AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID167	T <sub>DMO</sub>	MOSI Valid after SClock driving edge	–	–	15	ns	Guaranteed by characterization
SID168	T <sub>DSI</sub>	MISO Valid before SClock capturing edge	20	–	–	ns	Full clock, late MISO sampling. Guaranteed by characterization
SID169	T <sub>HMO</sub>	Previous MOSI data hold time	0	–	–	ns	Referred to Slave capturing edge. Guaranteed by characterization

**Table 15. Fixed SPI Slave Mode AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID170	T <sub>DMI</sub>	MOSI Valid before Sclock Capturing edge	40	–	–	ns	Guaranteed by characterization
SID171	T <sub>DSO</sub>	MISO Valid after Sclock driving edge	–	–	42 + 3 * T <sub>CPU</sub>	ns	T <sub>CPU</sub> = 1/F <sub>CPU</sub> . Guaranteed by characterization.
SID171A	T <sub>DSO_EXT</sub>	MISO Valid after Sclock driving edge in Ext Clk mode	–	–	48	ns	Guaranteed by characterization
SID172	T <sub>HSD</sub>	Previous MISO data hold time	0	–	–	ns	Guaranteed by characterization
SID172A	T <sub>SSELSCK</sub>	SSEL Valid to first SCK Valid edge	100	–	–	ns	Guaranteed by characterization

**Memory**
**Table 16. Flash AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.MEM#4	T <sub>ROWWRITE</sub> <sup>[3]</sup>	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID.MEM#3	T <sub>ROWERASE</sub> <sup>[3]</sup>	Row erase time	–	–	13	ms	–
SID.MEM#8	T <sub>ROWPROGRAM</sub> <sup>[3]</sup>	Row program time after erase	–	–	7	ms	–
SID178	T <sub>BULKERASE</sub> <sup>[3]</sup>	Bulk erase time (32 KB)	–	–	35	ms	–
SID180	T <sub>DEVPROG</sub> <sup>[3]</sup>	Total device program time	–	–	7.5	seconds	Guaranteed by characterization
SID181	F <sub>END</sub>	Flash endurance	100 K	–	–	cycles	Guaranteed by characterization
SID182	F <sub>RET1</sub>	Flash retention. T <sub>A</sub> ≤ 55 °C, 100 K P/E cycles	20	–	–	years	Guaranteed by characterization
SID182A	F <sub>RET2</sub>	Flash retention. T <sub>A</sub> ≤ 85 °C, 10 K P/E cycles	10	–	–	years	Guaranteed by characterization

**Note**

- It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

**System Resources**
*Power-on-Reset (POR) with Brown Out*
**Table 17. Imprecise Power On Reset (PRES)**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID185	V <sub>RISEIPOR</sub>	Rising trip voltage	0.80	–	1.50	V	Guaranteed by characterization
SID186	V <sub>FALLIPOR</sub>	Falling trip voltage	0.75	–	1.4	V	Guaranteed by characterization

**Table 18. Precise Power On Reset (POR)**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190	V <sub>FALLPPOR</sub>	BOD trip voltage in active and sleep modes	1.48	–	1.62	V	Guaranteed by characterization
SID192	V <sub>FALLDPSLP</sub>	BOD trip voltage in Deep Sleep	1.1	–	1.5	V	Guaranteed by characterization

*SWD Interface*
**Table 19. SWD Interface Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.SWD#1	F_SWDCCLK1	$3.3\text{ V} \leq V_{\text{DDIO}} \leq 5.5\text{ V}$	–	–	14	MHz	SWDCCLK $\leq$ 1/3 CPU clock frequency
SID.SWD#2	F_SWDCCLK2	$1.8\text{ V} \leq V_{\text{DDIO}} \leq 3.3\text{ V}$	–	–	7	MHz	SWDCCLK $\leq$ 1/3 CPU clock frequency
SID.SWD#3	T_SWDI_SETUP	$T = 1/f\text{ SWDCCLK}$	0.25*T	–	–	ns	Guaranteed by characterization
SID.SWD#4	T_SWDI_HOLD	$T = 1/f\text{ SWDCCLK}$	0.25*T	–	–	ns	Guaranteed by characterization
SID.SWD#5	T_SWDO_VALID	$T = 1/f\text{ SWDCCLK}$	–	–	0.5 * T	ns	Guaranteed by characterization
SID.SWD#6	T_SWDO_HOLD	$T = 1/f\text{ SWDCCLK}$	1	–	–	ns	Guaranteed by characterization

*Internal Main Oscillator*
**Table 20. IMO DC Specifications**
*(Guaranteed by Design)*

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I <sub>IMO</sub>	IMO operating current at 48 MHz	–	–	1000	μA	–

**Table 21. IMO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#13	F <sub>IMOTOL</sub>	Frequency variation at 24, 36, and 48 MHz (trimmed)	–	–	±2	%	–
SID226	T <sub>STARTIMO</sub>	IMO startup time	–	–	7	μs	Guaranteed by characterization
SID229	T <sub>JITRMSIMO</sub>	RMS jitter at 48 MHz	–	145	–	ps	Guaranteed by characterization
F <sub>IMO</sub>	–	IMO frequency	24	–	48	MHz	–

*Internal Low-Speed Oscillator*
**Table 22. ILO DC Specifications**

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I <sub>ILO</sub>	ILO operating current at 32 kHz	–	0.3	1.05	μA	Guaranteed by Characterization
SID233	I <sub>ILOLEAK</sub>	ILO leakage current	–	2	15	nA	Guaranteed by Design

**Table 23. ILO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234	T <sub>STARTILO</sub>	ILO startup time	–	–	2	ms	Guaranteed by characterization
SID236	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	Guaranteed by characterization
SID.CLK#5	F <sub>ILO</sub>	ILO Frequency	20	40	80	kHz	–

*Power Down*
**Table 24. PD DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.PD.1	Rp_std	DFP CC termination for default USB Power	64	80	96	μA	–
SID.PD.2	Rp_1.5A	DFP CC termination for 1.5A power	166	180	194	μA	–
SID.PD.3	Rp_3.0A	DFP CC termination for 3.0A power	304	330	356	μA	–
SID.PD.4	Rd	UFP CC termination	4.59	5.1	5.61	kΩ	–
SID.PD.5	Rd_DB	UFP Dead Battery CC termination on RD1 and CC2	4.08	5.1	6.12	kΩ	All supplies forced to 0 V and 0.6 V applied at RD1 or CC2
SID.PD.6	R <sub>A</sub>	Power cable termination	0.8	1.0	1.2	kΩ	All supplies forced to 0 V and 0.2 V applied at V <sub>CONN1</sub> or V <sub>CONN2</sub>
SID.PD.7	Ra_OFF	Power cable termination - Disabled	0.4	0.75	–	MΩ	2.7 V applied at V <sub>CONN1</sub> or V <sub>CONN2</sub> with R <sub>A</sub> disabled
SID.PD.8	Rleak_1	V <sub>CONN</sub> leaker for 0.1-μF load	–	–	216	kΩ	Managed Active Cable (MAC) discharge
SID.PD.9	Rleak_2	V <sub>CONN</sub> leaker for 0.5-μF load	–	–	41.2	kΩ	
SID.PD.10	Rleak_3	V <sub>CONN</sub> leaker for 1.0-μF load	–	–	19.6	kΩ	
SID.PD.11	Rleak_4	V <sub>CONN</sub> leaker for 2.0-μF load	–	–	9.8	kΩ	
SID.PD.12	Rleak_5	V <sub>CONN</sub> leaker for 5.0-μF load	–	–	4.1	kΩ	
SID.PD.13	Rleak_6	V <sub>CONN</sub> leaker for 10-μF load	–	–	2.0	kΩ	
SID.PD.14	Ileak	Leaker on V <sub>CONN1</sub> and V <sub>CONN2</sub> for discharge upon cable detach	150	–	–	μA	–

Analog to Digital Converter

**Table 25. ADC DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.ADC.1	Resolution	ADC resolution	–	8	–	bits	Guaranteed by characterization
SID.ADC.2	INL	Integral non-linearity	–1.5	–	1.5	LSB	Guaranteed by characterization
SID.ADC.3	DNL	Differential non-linearity	–2.5	–	2.5	LSB	Guaranteed by characterization
SID.ADC.4	Gain Error	Gain error	–1	–	1	LSB	Guaranteed by characterization

**Table 26. ADC AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.ADC.5	SLEW_Max	Rate of change of sampled voltage signal	–	–	3	V/ms	Guaranteed by characterization



## Ordering Information

The EZ-PD CCG2 part numbers and features are listed in [Table 27](#).

**Table 27. EZ-PD CCG2 Ordering Information**

Part Number	Application	Type-C Ports	Termination Resistor	Role	Package
CYPD2103-20FNXIT	Cable	1	R <sub>A</sub> <sup>[4]</sup>	Cable	20-ball CSP
CYPD2103-14LHXIT	Cable	1	R <sub>A</sub> <sup>[4]</sup>	Cable	14-pin DFN
CYPD2104-20FNXIT	Accessory	1	R <sub>D</sub> <sup>[5]</sup>	Accessory	20-ball CSP
CYPD2105-20FNXIT	Active Cable	1	R <sub>A</sub> <sup>[4]</sup>	Active Cable	20-ball CSP
CYPD2119-24LQXIT	C-DP	1	R <sub>D</sub> <sup>[5]</sup>	UFP	24-pin QFN
CYPD2120-24LQXIT	C-HDMI	1	R <sub>D</sub> <sup>[5]</sup>	UFP	24-pin QFN
CYPD2121-24LQXIT	Dock/Monitor Upstream port	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	24-pin QFN
CYPD2122-20FNXIT	Tablet	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	20-ball CSP
CYPD2122-24LQXIT	Notebook	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	24-pin QFN
CYPD2125-24LQXIT	Dock/Monitor Downstream port	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN
CYPD2134-24LQXIT	DFP	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN
CYPD2134-24LQXQT	DFP	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN

## Ordering Code Definitions



### Notes

4. Termination resistor denoting an EMCA.
5. Termination resistor denoting an accessory or upstream facing port.
6. Termination resistor denoting a downstream facing port.

**Packaging**

**Table 28. Package Characteristics**

Parameter	Description	Conditions	Min	Typ	Max	Units
T <sub>A</sub>	Operating ambient temperature	Industrial	-40	25	85	°C
		Extended Industrial			105	°C
T <sub>J</sub>	Operating junction temperature	Industrial	-40	-	100	°C
		Extended Industrial			125	°C
T <sub>JA</sub>	Package θ <sub>JA</sub> (20-ball WLCSP)	-	-	66	-	°C/W
T <sub>JC</sub>	Package θ <sub>JC</sub> (20-ball WLCSP)	-	-	0.7	-	°C/W
T <sub>JA</sub>	Package θ <sub>JA</sub> (14-pin DFN)	-	-	31	-	°C/W
T <sub>JC</sub>	Package θ <sub>JC</sub> (14-pin DFN)	-	-	59	-	°C/W
T <sub>JA</sub>	Package θ <sub>JA</sub> (24-pin QFN)	-	-	22	-	°C/W
T <sub>JC</sub>	Package θ <sub>JC</sub> (24-pin QFN)	-	-	29	-	°C/W

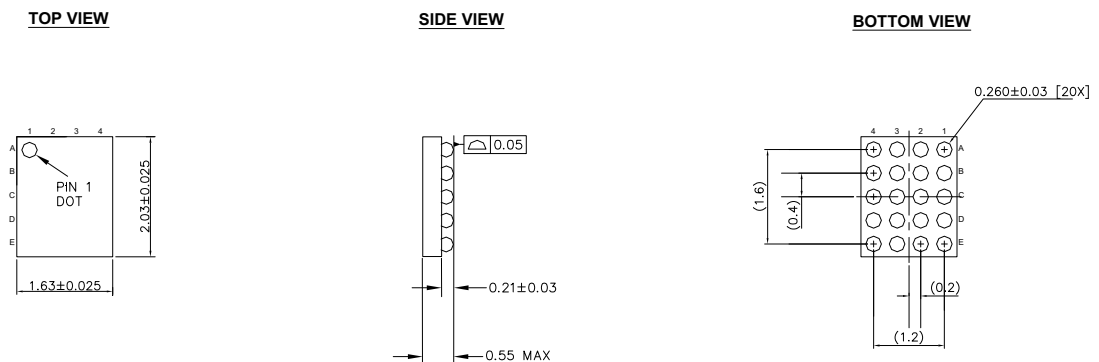
**Table 29. Solder Reflow Peak Temperature**

Package	Maximum Peak Temperature	Maximum Time within 5 °C of Peak Temperature
20-ball WLCSP	260 °C	30 seconds
14-pin DFN	260 °C	30 seconds
24-pin QFN	260 °C	30 seconds

**Table 30. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2**

Package	MSL
20-ball WLCSP	MSL 1
14-pin DFN	MSL 3
24-pin QFN	MSL 3

**Figure 15. 20-ball WLCSP (1.63 × 2.03 × 0.55 mm) FN20B Package Outline, 001-95010**



**NOTES:**

1. REFERENCE JEDEC PUBLICATION 95, DESIGN GUIDE 4.18
2. ALL DIMENSIONS ARE IN MILLIMETERS

001-95010 \*A

**Figure 16. 14-pin DFN (2.5 × 3.5 × 0.6 mm), LH14A, 0.95 × 3.00 E-Pad (Sawn) Package Outline, 001-96312**



**NOTES :**

1. HATCH AREA IS SOLDERABLE EXPOSED METAL
2. ALL DIMENSIONS ARE IN MILLIMETERS

001-96312 \*\*

**Figure 17. 24-Pin QFN (4 × 4 × 0.55 mm), LQ24A, 2.65 × 2.65 E-Pad (Sawn) Package Outline, 001-13937**



**NOTES :**

1.  HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT : 29 ± 3 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 \*F

## Acronyms

**Table 31. Acronyms Used in this Document**

Acronym	Description
ADC	analog-to-digital converter
API	application programming interface
ARM®	advanced RISC machine, a CPU architecture
CC	configuration channel
CCG2	Cable Controller Generation 2
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
CS	current sense
DFP	downstream facing port
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DRP	dual role port
EEPROM	electrically erasable programmable read-only memory
EMCA	a USB cable that includes an IC that reports cable characteristics (e.g., current rating) to the Type-C ports
EMI	electromagnetic interference
ESD	electrostatic discharge
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output
IC	integrated circuit
IDE	integrated development environment
I <sup>2</sup> C, or IIC	Inter-Integrated Circuit, a communications protocol
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
I/O	input/output, see also GPIO
LVD	low-voltage detect
LVTTTL	low-voltage transistor-transistor logic
MCU	microcontroller unit
NC	no connect
NMI	nonmaskable interrupt

**Table 31. Acronyms Used in this Document (continued)**

Acronym	Description
NVIC	nested vectored interrupt controller
opamp	operational amplifier
OCP	overcurrent protection
OVP	overvoltage protection
PCB	printed circuit board
PD	power delivery
PGA	programmable gain amplifier
PHY	physical layer
POR	power-on reset
PRES	precise power-on reset
PSoC®	Programmable System-on-Chip™
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RX	receive
SAR	successive approximation register
SCL	I <sup>2</sup> C serial clock
SDA	I <sup>2</sup> C serial data
S/H	sample and hold
SPI	Serial Peripheral Interface, a communications protocol
SRAM	static random access memory
SWD	serial wire debug, a test protocol
TX	transmit
Type-C	a new standard with a slimmer USB connector and a reversible cable, capable of sourcing up to 100 W of power
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
USB	Universal Serial Bus
USBIO	USB input/output, CCG2 pins used to connect to a USB port
XRES	external reset I/O pin

**Document Conventions**

**Units of Measure**

**Table 32. Units of Measure**

Symbol	Unit of Measure
°C	degrees Celsius
Hz	hertz
KB	1024 bytes
kHz	kilohertz
kΩ	kilo ohm
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
μA	microampere
μF	microfarad
μs	microsecond
μV	microvolt
μW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
V	volt

**Document History Page**

Description Title: EZ-PD™ CCG2 Datasheet USB Type-C Port Controller				
Document Number: 001-93912				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
*E	4680071	GAYA	03/07/2015	Release to web
*F	4718374	AKN	04/09/2015	Added 24-pin QFN pin and package information. Added DRP and DFP Application diagrams
*G	4774142	AKN	06/15/2015	Changed datasheet status from Preliminary to Final. Updated Logic Block Diagram. Changed number of GPIOs to 10 and added a note about the number of GPIOs varying depending on the package. Updated Power and Digital Peripherals section. Updated Application diagrams. Added SID.PWR#1_A parameter. Added CYPD2122-20FNXIT part in Ordering Information. Removed Errata.
*H	4979175	VGT	10/23/2015	Updated Figure 1 and Figure 5. Added VCC_ABS spec and updated the SID.ADC.4 parameter. Added "Guaranteed by characterization" note for the following specs: SID.GIO#16, SID.GIO#17, SID.XRES#3, SID 160 to SID 172A, SID 2226, SID 229, SID.ADC.1 to SID.ADC.5.
*I	5028128	VGT	12/04/2015	Updated <a href="#">Application Diagrams</a> : Added <a href="#">Figure 12</a> . Added <a href="#">Figure 13</a> . Added <a href="#">Figure 14</a> . Updated <a href="#">Ordering Information</a> . Added part numbers CYPD2119-24LQXIT, CYPD2120-24LQXIT, CYPD2121-24LQXIT, CYPD2125-24LQXIT.
*J	5186972	VGT	03/28/2016	Updated temperature ranges in <a href="#">Features</a> . Updated <a href="#">Table 28</a> . Updated <a href="#">Ordering Information</a> .

## Sales, Solutions, and Legal Information

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